TARIF IFTEC STANDARDS IPC Au 01 janvier 2025
Valide jusqu'au 03/02/2025
Coût Transport / Emballage

Colissimo France :		Colissimo Etranger (zone A - Zone B) :		
poids < 500g	18€	32€	45€	poids < 500g
poids > 500g < 1kg 1	22€	37€	53€	poids > 500g < 1kg
poids > 1kg < 2kg	27€	43€	58€	poids > 1kg < 2kg
poids > 2kg < 5kg	35€	53€	73€	poids > 2kg < 5kg
poids > 5kg < 10kg	55€	82€	117€	poids > 5kg < 10kg

		REFERENCE IPC	POIDS	PRIX	TITRE
1072	CD	IPC-1072(E)1	54 g	113€	Intellectual Property Protection in Electronic Assembly Manufacturing
	D	IPC-1072(D)1	-	123€	
1602A	LIV	IPC-1602A	110 g	211€	Standard for Printed Board Handling and Storage
	D	IPC-1602A(D)1	-	192€	
1782B	LIV	IPC-1782B	150	217€	Standard for Manufacturing and Supply Chain Traceability of Electronic Products
	D	IPC-1782B	-	196€	
1791D	LIV	IPC-1791D	80	194€	Trusted Electronic Designer, Fabricator and Assembler Requirements
	D	IPC-1791D(D)1	-	169€	
2141A	D	IPC-2141A(D)1	-	163€	Design Guide for High-Speed Controlled Impedance Circuit Boards
2152	D	IPC-2152(D)1	-	203€	Standard for Determining Current Carrying Capacity in Printed Board Design
2221C	LIV	IPC-2221C	422	262€	Generic Standard on Printed Board Design
	D	IPC-2221C(D)1	-	235€	
2222B	LIV	IPC-2222B	120	182€	Sectional Design Standard for Rigid Organic Printed Boards
	D	IPC-2222B(D)1	-	167€	
2222B-FR	LIV	IPC-2222B-FR	120	313€	Norme Sectionnelle de Conception pour les Circuits Imprimés Organiques Rigides (French Language)
	D	IPC-2222B-FR(D)1	-	279€	

		REFERENCE IPC	POIDS	PRIX	TITRE
2223E	LIV	IPC-2223E	200	225€	Sectional Design Standard for Flexible / Rigid Flexible Printed Boards
	D	IPC-2223E(D)1	-	203€	
2225	LIV	IPC-2225(E)1	54	153€	Sectional Design Standard for Organic Multichip Modules (MCM-L) and MCM-L Assemblies
	D	IPC-2225(D)1	-	163€	
2226A	D	IPC-2226A(D)1	-	203€	Sectional Design Standard for High Density Interconnect (HDI) Boards
2228	LIV	IPC-2228	400	150€	Sectional Design Standard for High Frequency (RF/Microwave) Printed Boards
	D	IPC-2228(D)1	-	139€	
2231A	LIV	IPC-2231A	160	218€	DFX Guidelines
	D	IPC-2231A(D)1	-	186€	
2251	CD	IPC-2251(E)1	54	153€	Design Guide for the Packaging of High Speed Electronic Circuits
	D	IPC-2251(D)1	-	163€	
2291	CD	IPC-2291(E)1	54	113€	Design Guideline for Printed Electronics
	D	IPC-2291(D)1	-	123€	
2292A	LIV	IPC-2292A	300	225€	Design Standard for Printed Electronics on Flexible Substrates
	D	IPC-2292A(D)1	-	203€	
2581C	LIV	IPC-2581C	710	225€	Generic Requirements for Printed Board Assembly Products Manufacturing Description Data an Transfer Methodology
	D	IPC-2581C(D)1	-	203€	
2591-V1.7	LIV	IPC-2591-V1.7	250	224€	Connected Factory Exchange (CFX)
	D	IPC-2591-V1.7(D)1	-	201€	
2591-FR	D	IPC-2591-FR(D)1	-	290€	Echanges au Sein d'une Usine Connectée (CFX)
2611	D	IPC-2611(D)1	-	123€	Generic Requirements for Electronic Product Documentation
2612	CD	IPC-2612(E)1	54	113€	Sectional Requirements for Electronic Diagramming Documentation (Schematic and Logic Descriptions)
	D	IPC-2612(D)1	-	123€	

		REFERENCE IPC	POIDS	PRIX	TITRE
2612-1	CD	IPC-2612-1(E)1	54	153€	Sectional Requirements for Electronic Diagramming Symbol Generation Methodology
	D	IPC-2612-1(D)1	-	163€	
2614	D	IPC-2614(D)1	-	163€	Sectional Requirements for Board Fabrication Documentation
2615	D	IPC-2615(D)1	-	163€	Printed Board Dimensions and Tolerences
4101E-WAM1	LIV	IPC-4101E-WAM1	490	234€	Specification for Base Materials for Rigid and Multilayer Printed Boards
	D	IPC-4101E-WAM1(D)1	-	203€	
4103B	D	IPC-4103B(D)1	-	169€	Specification for High Density Interconnect (HDI) and Microvia Materials
4104	D	IPC-4104(D)1	-	163€	Specification for High Density Interconnect (HDI) and Microvia Materials
4121	CD	IPC-4121(E)1	54	113€	Guidelines for Selecting Core Construction for Multilayer Printed Wiring Board Applications
	D	IPC-4121(D)1	-	123€	
4202C	LIV	IPC-4202C	100	131€	Specification for Flexible Base Dialectics for use in Flexible Printed Boards
	D	IPC-4202C(D)1	-	123€	
4203B	D	IPC-4203B(D)1	-	169€	Cover and Bonding Material for Flexible Printed Circuitry
4204B	D	IPC-4204B(D)1	-	169€	Flexible Metal-Clad Dielectrics for Use in Fabrication of Flexible Printed Boards
4412C	LIV	IPC-4412C	100	131€	Specification for Finished Fabric Woven from "E" Glass for Printed Boards
	D	IPC-4412C(D)1	-	123€	
4552B	LIV	IPC-4552B	540	263€	Specification for Electroless Nickel/Immersion Gold (ENIG) Plating for Printed Circuit Boards
	D	IPC-4552B(D)1	-	226€	

		REFERENCE IPC	POIDS	PRIX	TITRE
4553A	CD	IPC-4553A(E)1	54	193€	Specification for Immersion Silver Plating for Printed Boards
	D	IPC-4553A(D)1	-	203€	
IPC-4554-WAM1	D	IPC-4554-WAM1(D)1	-	203€	Specification for Immersion Tin Plating for Printed Circuit Boards - With Amendment 1
4555	LIV	IPC-4555	240	150€	Performance Specification for High Temperature Organic Solderability Preservatives (OSP) for Printed Boards
	D	IPC-4555(D)1	-	139€	
4556	CD	IPC-4556(E)1	54	193€	Specification for Electroless Nickel/Electroless Palladium/Immersion Gold (ENEPIG) Plating for Printed Circuit Boards
	D	IPC-4556(D)1	-	203€	
4562B	LIV	IPC-4562B	150	194€	Metal Foil for Printed Board Applications
	D	IPC-4562B(D)1	-	163€	
4591A	D	IPC-4591A(D)1	-	125€	Requirements for Printed Electronics Functional Conductive Materials
4781	D	IPC-4781(D)1	-	123€	Qualification and Performance Specification of Permanent, Semo-Permanent and Temporary Legend and/or Marking Ink
4921A	D	IPC-4921A(D)1	-	123€	Requirements for Printed Electronics Base Materials (Substrates)
5262	LIV	IPC-5262	70	184€	Design, Critical Process and Acceptance Requirements for Polymeric Applications
	D	IPC-5262(D)1	-	169€	
5703	D	IPC-5703(D)1	-	123€	Cleanliness Guidelines for Printed Board Fabricators
5704	D	IPC-5704(D)1	-	123€	Cleanliness Requirements for Unpopulated Printed Boards
6011	D	IPC-6011(D)1	-	123€	Generic Performance Specification for Printed Boards

		REFERENCE IPC	POIDS	PRIX	TITRE
6012F	LIV	IPC-6012F	140	234€	Qualification and Performance Specification for Rigid Printed Boards
	D	IPC-6012F(D)1	-	203€	
6012D-FR	CD	IPC-6012D-FR(E)1	54	304€	Spécification de la Qualification et des Performances des Circuits Imprimés Rigides
	D	IPC-6012D-FR(D)1	-	314€	
6012DS-FR	D	IPC-6012DS-FR(D)1	-	171€	Avenant pour les Applications Spatiales et Aéronautiques Militaires de l'IPC-6012D
6013E	LIV	IPC-6013E	165	225€	Qualification and Performance Specification for Flexible / Rigid-Flexible Printed Boards
	D	IPC-6013E(D)1	-	203€	
6015	CD	IPC-6015(E)1	54	113€	Qualification & Performance Specification for Organic Multichip Module (MCM-L) Mounting & Interconnecting Structures
	D	IPC-6015(D)1	-	123€	
6017A	LIV	IPC-6017A	100	131€	Qualification and Performance Specification for Printed Boards Containing Embedded Active and Passive Circuitry
	D	IPC-6017A(D)1	-	123€	
6018D	LIV	IPC-6018D	180	225€	Qualification and Performance Specification for High Frequency (Microwave) Printed Boards
	D	IPC-6018D(D)1	-	203€	
6901	D	IPC/JPCA-6901(D)1	-	123€	Application Categories for Printed Electronics
6903A	D	IPC-6903A(D)1	-	125€	Terms and Definitions for the Design and Manufacture of Printed Electronics
7091A	LIV	IPC-7091A	400	225€	Design and Assembly Process Implementation of 3D Components
	D	IPC-7091A(D)1	-	203€	
7092A	LIV	IPC-7092A	490	225€	Design and Assembly Process Implementation for Embedded Components
	D	IPC-7092A(D)1	-	203€	

		REFERENCE IPC	POIDS	PRIX	TITRE
7093A	LIV	IPC-7093A	500	225€	Design and Assembly Process Implementation for Bottom Termination Components (BTCs)
	D	IPC-7093A(D)1	-	203€	
7094A	D	IPC-7094A(D)1	-	203€	Design and Assembly Process Implementation for Flip Chip and Die Size Components
7095E	LIV	IPC-7095E	770	225€	Design and Assembly Process Implementation for BGAs, with Amendment 1
	D	IPC-7095E(D)1	-	203€	
7351B	D	IPC-7351B(D)1	-	203€	Generic Requirements for Surface Mount Design and Land Pattern Standard
7525C	LIV	IPC-7525C	130	131€	Stencil Design Guidelines
	D	IPC-7525C(D)1	-	123€	
7527	D	IPC-7527(D)1	-	203€	Requirements for Solder Paste Printing
7530A	D	IPC-7530A(D)1	-	203€	Guidelines for Temperature Profiling for Mass Soldering Processes (Reflow & Wave)
7711/21D	LIV	IPC-7711/21D	1350	476€	Rework, Modification and Repair of Electronic Assemblies
	D	IPC-7711/21D(D)1	-	398€	
7711/21C-FR	D	IPC-7711/21C-FR(D)1	-	572€	Reprise, Modification et Réparation des Assemblages Electroniques
7711/21C-AM1-FR	LIV	IPC-7711/21C-AM1-FR	50	75€	Amendement - Reprise, Modification et Réparation des Assemblages Electroniques
	D	IPC-7711/21C-AM1-FR(D)1	-	68€	
8497-1	D	IPC-8497-1(D)1	-	203€	Cleaning Methods and Contamination Assessment for Optical Assembly
8921	D	IPC-8921(D)1	-	192€	Requirements for Woven and Knitted Electronic Textiles (E-Textiles) Integrated with Conductive Fibers, Conductive Yarns and / or Wires

		REFERENCE IPC	POIDS	PRIX	TITRE
9111	D	IPC-9111(D)1	-	236€	Troubleshooting for Printed Board Assembly Processes
9121A	LIV	IPC-9121A	950	476€	Troubleshooting for PCB Fabrication Processes
	D	IPC-9121A(D)1	-	412€	
9191	CD	IPC-9191(E)1	54	153€	General Guidelines for Implementation of Statistical Process Control (SPC)
	D	IPC-9191(D)1	-	163€	
9201A	D	IPC-9201A(D)1	-	203€	Surface Insulation Resistance Handbook
9202A	LIV	IPC-9202A	40	131€	Material and Process Characterization / Qualification Test Protocol for Assessing Electrochemical Performance
	D	IPC-9202A(D)1	-	123€	
9203A	LIV	IPC-9203A	200	225€	Users Guide to IPC-9202 and the IPC-B-52 Standard Test Vehicle
	D	IPC-9203A(D)1	-	203€	
9204	CD	IPC-9204(E)1	54	104€	Guideline on Flexibility and Stretchability Testing for Printed Electronics
	D	IPC-9204(D)1	-	114€	
9241	D	IPC-9241(D)1	-	203€	Guidelines for Microsection Preparation
9252B	D	IPC-9252B(D)1	-	123€	Requirements for Electrical Testing of Unpopulated Printed Boards
9257	LIV	IPC-9257	105	182€	Requirements for Electrical Testing of Flexible Printed Electronics
	D	IPC-9257(D)1	-	167€	
9301	D	IPC-9301(D)1	-	194€	IPC/JEDEC Numerical Analysis Guidelines for Microelectronics Packaging Design and Reliability
9505	D	IPC-9505(D)1	-	125€	Guideline Methodology for Assessing Component and Cleaning Materials Compatibility
9641	CD	IPC-9641(E)1	54	113€	High Temperature Printed Board Flatness Guideline
	D	IPC-9641(D)1	-	123€	

		REFERENCE IPC	POIDS	PRIX	TITRE
9691B	D	IPC-9691B(D)1	-	203€	User Guide for the IPC-TM-650, Method 2.6.25, Conductive Anodic Filament (CAF) Resistance Test (Electrochemical Migration Testing)
9701A	CD	IPC-9701A(E)1	54	113€	Performance Test Methods and Qualification Requirements for Surface Mount Solder Attachments
	D	IPC-9701A(E)1	-	123€	
9704A	CD	IPC-9704A(E)1	54	193€	Printed Circuit Assembly Strain Gage Test Guideline
	D	IPC-9704A(E)1	-	203€	
9708	D	IPC-9708(D)1	-	203€	Test Methods for Characterization of Printed Board Assembly Pad Cratering
9709A	LIV	IPC-9709A	59	225€	Guidelines for Acoustic Emission Measurement Method during Mechanical Testing
	D	IPC-9709A(D)1	-	203€	
9797A	LIV	IPC-9797A	180	212€	Press-fit Standard for Automotive Requirements and other High-Reliability Applications
	D	IPC-9797A(D)1	-	192€	
HERMES-9852	LIV	IPC-HERMES-9852 V1.6	200	211€	The Global Standard for Machine-to-Machine Communication in SMT Assembly
	D	IPC-HERMES-9852(D)1 V1.6	-	192€	
A-600K	LIV	IPC-A-600K	760	363€	Acceptability of Printed Boards
	D	IPC-A-600K(D)1	-	302€	
A-600K-FR	LIV	IPC-A-600K-FR	760	522€	Acceptabilité des Circuits Imprimés (French language)
	D	IPC-A-600K-FR(D)1	-	435€	
A-610J	LIV	IPC-A-610J	1500	363€	Acceptability of Electronic Assemblies
	D	IPC-A-610J(D)1	-	302€	
A-610H-FR	LIV	IPC-A-610H-FR	1500	522€	Acceptabilité des assemblages électroniques (French Language)
	D	IPC-A-610H-FR(D)1	-	435€	
A-620E	LIV	IPC/WHMA-A-620E	1400	363€	Requirements and Acceptance for Cable and Wire Harness Assemblies
	D	IPC/WHMA-A-620E(D)1	-	302€	
A-620D-FR	LIV	IPC/WHMA-A-620D-FR	1480	522€	Exigences et Acceptation des Assemblages de Câbles et de Faisceaux de Fils (French Language)
	D	IPC/WHMA-A-620D-FR(D)1	-	435€	

		REFERENCE IPC	POIDS	PRIX	TITRE
A-630	D	IPC-A-630(D)1	-	203€	Acceptability Standard for Manufacture, Inspection and Testing of Electronic Enclosures
IPC-A-640A	LIV	IPC-A-640A	700	225€	Acceptance Requirements for Optical Fiber, Optical Cable, and Hybrid Wiring Harness Assemblies
	D	IPC-A-640A(D)1	-	203€	
AJ-820A	LIV	IPC-AJ-820A	1028	225€	Assembly & Joining Handbook
	D	IPC-AJ-820A(D)1	-	203€	
CC-830C	D	IPC-CC-830C(D)1	-	123€	Qualification and Performance of Electrical Insulating Compound for Printed Wiring Assemblies
CH-65B	D	IPC-CH-65B(D)1	-	203€	Guidelines for Cleaning of Printed Boards and Assemblies
D-620A	D	IPC-D-620A(D)1	-	203€	Design and Critical Process Requirements for Cable and Wiring Harnesses (kit products : WP-113A, WP114A, WP-116A)
D-640A	LIV	IPC-D-640A	200	225€	Design and Critical Process Requirements for Optical Fiber, Optical Cable and Hybrid Wiring Harness assemblies
	D	IPC-D-640A(D)1	-	203€	
IPC-DR-DES-2022	LIV	IPC-DR-DES-2022	100	138€	PCB Design Desk Reference 2022 Edition
IPC-DR-DES-2022-FR	LIV	IPC-DR-DES-2022-FR	100	138€	PCB Design Desk Reference 2022 Edition
IPC-QRG-18J	LIV	IPC-QRG-18J	183	85€	Component Identification Training and Reference Guide
	D	IPC-QRG-18J(D)1	-	83€	
QRG-PTH-H	LIV	IPC-QRG-PTH-H	100	85€	Through-Hole SolderJoint Evaluation Training & Reference Guide
	D	IPC-QRG-PTH-H(D)1	-	83€	
IPC-SMT-H	LIV	IPC-QRG-SMT-H	115	85€	Surface Mount Solder Joint Evaluation Training & Reference Guide
	D	IPC-QRG-SMT-H(D)1	-	83€	
QRG-WHA-D	LIV	IPC-QRG-WHA-D	160	85€	Wire Harness Assembly Training & Reference Guide
	D	IPC-QRG-WHA-D(D)1	-	83€	

		REFERENCE IPC	POIDS	PRIX	TITRE
HDBK-001H	LIV	IPC-HDBK-001H	600	283€	Handbook and Guide to Supplement IPC-J-STD-001
	D	IPC-HDBK-001H(D)1	-	253€	
HDBK-005	D	IPC-HDBK-005(D)1	-	203€	Guide to Solder Paste Assessment
HDBK-620	LIV	IPC-HDBK-620	870	265€	Handbook and Guide to IPC-D-620 & IPC/WHMA-A-620
	D	IPC-HDBK-620(D)1	-	236€	
HDBK-630	D	IPC-HDBK-630(D)1	-	203€	Guidelines for Design, Manufacture, Inspection and Testing of Electronic Enclosures
HDBK-830A	D	IPC-HDBK-830A(D)1	-	203€	Guidelines for Design, Selection and Application of Conformal Coatings
HDBK-840	CD	IPC-HDBK-840(E)1	54	193€	Solder Mask Handbook
	D	IPC-HDBK-840(D)1	-	203€	
HDBK-850	D	IPC-HDBK-850(D)1	-	203€	Guidelines for Design, Selection and Application of Potting Materials and Encapsulation Processes Used for Electronics Printed Circuit Board Assembly
HDBK-9798	LIV	IPC-HDBK-9798	400	184€	Handbook for Press-Fit Standard for Automotive Requirements and other High-Reliability Applications
	D	IPC-HDBK-9798(D)1	-	169€	
JP002	CD	IPC-JP002(E)1	54	113€	JEDEC/IPC Current Tin Whiskers Theory and Mitigation Practices Guideline
	D	IPC-JP002(D)1	-	123€	
J-STD-001J	LIV	IPC-J-STD-001J	300	290€	Requirements for Soldered Electrical and Electronic Assemblies
	D	IPC-J-STD-001J(D)1	-	228€	
J-STD-001HFR	LIV	IPC-J-STD-001H-FR	300	405€	Exigences Relatives aux Assemblages Electroniques et Electriques Brasés (French Language)
	D	IPC-J-STD-001H-FR(D)1	-	338€	
J-STD-002E	D	IPC-J-STD-002E(D)1	-	169€	EIA/IPC/JEDEC J-STD-002D Solderability Tests for Component Leads, Terminations, Lugs, Terminals and Wires
J-STD-003D	LIV	IPC-J-STD-003D	250	225€	Solderability Tests for Printed Boards
	D	IPC-J-STD-003D(D)1	-	203€	

		REFERENCE IPC	POIDS	PRIX	TITRE
J-STD-004D	LIV	IPC-J-STD-004D	160	225€	Requirements for Soldering Fluxes
	D	IPC-J-STD-004D(D)1	-	203€	
J-STD-005B	LIV	IPC-J-STD-005B	100	131€	Solderability Tests for Printed Boards
	D	IPC-J-STD-005B(D)1	-	123€	
J-STD-006C	D	IPC-J-STD-006C(D)1	-	123€	Requirements for Electronic Grade Solder Alloys and Fluxed and Non-Fluxed Solid Solders for Electronic Soldering Applications
J-STD-020F	LIV	IPC-J-STD-020F	120	131€	IPC/JEDEC Moisture/Reflow Sensitivity Classification for Non-hermetic Surface Mount Devices
	D	IPC-J-STD-020F(D)1	-	123€	
J-STD-030A	CD	IPC-J-STD-030A(E)1	54	193€	Selection and Application of Board Level Underfill Materials
	D	IPC-J-STD-030A(D)1	-	203€	
J-STD-033D	D	D	-	123€	Handling, Packing, Shipping and Use of Moisture/Reflow Sensitive Surface Mount Devices
J-STD-075A	LIV	IPC-J-STD-075A	160	133€	125€
	D	IPC-J-STD-075A(D)1	-	125€	
J-STD-609B	D	IPC-J-STD-609B(D)1	-	123€	Marking and Labeling of Components, PCBs and PCBAs to Identify Lead (Pb), Lead-Free (PbFree) and Other Attributes
PE-740A	CD	IPC-PE-740A(E)1	54	193€	Troubleshooting for Printed Board Manufacture and Assembly
	D	IPC-PE-740A(D)1	-	203€	
QE-605A	D	IPC-QE-605A(D)1	-	203€	Printed Board Quality Evaluation
SM-784	D	IPC-SM-784(D)1	-	163€	Guidelines for Chip-on-Board Technology Implementation
SM-785	CD	IPC-SM-785(E)1	54	153€	Guidelines for Accelerated Reliability Testing of Surface Mount Attachments
	D	IPC-SM-785(D)1	-	163€	
SM-817A	D	IPC-SM-817A(D)1	-	123€	General Requirements for Dielectric Surface Mount Adhesives

		REFERENCE IPC	POIDS	PRIX	TITRE
SM-840E	D	IPC-SM-840E(D)1	-	123€	Qualification and Performance Specification of Permanent Solder Mask and Flexible Cover Materials
T-50N	LIV	IPC-T-50N	330	225€	Terms and Definitions for Interconnecting and Packaging Electronic Circuits
	D	IPC-T-50N(D)1	-	203€	
T-50M-FR	D	IPC-T-50M-FR(D)1	-	289€	Termes et Définitions pour les Circuits Electroniques Imprimés et Assemblés (French Language)
IPC-T-51	LIV	IPC-T-51	80	131€	Terms and Definitions for Design and Manufacture of Printed Electronics
	D	IPC-T-51(D)1	-	123€	
WP-019B	LIV	IPC-WP-019B	103	126€	An Overview on the Global Change in Ionic Cleanliness Requirements
	D	IPC-WP-019B(D)1	-	119€	
WP-019A-FR	D	IPC-WP-019A-FR(D)1	-	165€	Présentation des Modifications Générales des Exigences en Matière de Propreté ionique